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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: TIEN-JEN CHIANG, ET AL.
Serial No.: 10/707,047
Filed: November 18, 2003
For: METHOD FOR SELECTIVE ELECTRO-
PLATING OF SEMICONDUCTOR
DEVICE I/O PADS USING A
TITANIUM-TUNGSTEN SEED LAYER

) Group Art Unit: 1753
)
) Examiner: Van, L.
) Confirmation No.: 1046
)

AMENDMENT AFTER FINAL

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Entered per
RCE filed
4/10/06 MA

In response to the Final Office Action mailed February 27, 2006, please amend
the Application as follows: